Devcon 5 Minute® Epoxy

Epoxy; Epoxide

Devcon

Message:

A rapid-curing, general purpose adhesive/encapsulant. Intended Use: Bonds metals, fabrics, ceramics, glass, wood, and concrete (in combinations) Product features: 100% reactive, no solvents Good solvent resistance Bonds metals, fabrics, wood, and concrete

General Information			
Features	Solvent resistance		
	Fast curing		
	General		
Uses	General		
	Bonding		
	Adhesive		
Appearance	Amber		
Processing Method	Enclosure		
Physical	Nominal Value	Unit	Test Method
Specific Volume	0.907	cm³/g	
Solid content-by Volume	100	%	
Impact Resistance	11.6	kJ/m²	
Service Temperature - Dry	-40 - 93	°C	
Work Time	3.0 - 6.0	min	
Tensile Shear Adhesion	13.1	MPa	ASTM D1002
Density ¹	1.10	g/cm³	
Hardness	Nominal Value	Unit	Test Method
Durometer Hardness (Shore D)	85		ASTM D2240
Mechanical	Nominal Value	Unit	
Tensile Elongation (Break)	1.0	%	
Electrical	Nominal Value	Unit	Test Method
Dielectric Strength	19	kV/mm	ASTM D149
Thermoset	Nominal Value	Unit	Test Method
Thermoset Components			

Component a	Mixing ratio by capacity: 1.0)	
	Mixing ratio by weight: 1.0		
Component B	Mixing ratio by capacity: 1.0		
Thermoset Mix Viscosity	10000	cP	
Additional Information	Nominal Value	Unit	Test Method
Cured 7 days @ 75°F			
Uncured Properties	Nominal Value	Unit	Test Method
Curing Time (22°C)	12	hr	
NOTE			
1.	Mixed		

The information and data on this page are provided by manufacturers and document providers. SHANGHAI SUSHENG assumes no legal liability. It is strongly recommended to verify all technical data with material suppliers before final material selection. All rights belong to the original authors. If any infringement occurs, please contact us immediately.

Recommended distributors for this material

Susheng Import & Export Trading Co.,Ltd.

Tel: +86 21 5895 8519

Phone: +86 13424755533

Email: sales@su-jiao.com

No. 215, Lianhe North Road, Fengxian District, Shanghai, China

